



SOT261-2

plastic led chip carrier; 28 leads

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	PLCC28
Package type industry code	PLCC28
Package style descriptive code	PLCC (plastic led chip carrier)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	112E08
JEDEC package outline code	MS-018
JEITA package outline code	EDR-7319
Mounting method type	S (surface mount)
Issue date	15-11-2001

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.43	-	11.48	11.58	mm
E	package width	11.43	-	11.48	11.58	mm
A	seated height	4.19	-	4.57	4.57	mm
A ₂	package height	[tbd]	-	3.86	[tbd]	mm
n ₂	actual quantity of termination	-	-	28	-	



2. Package outline

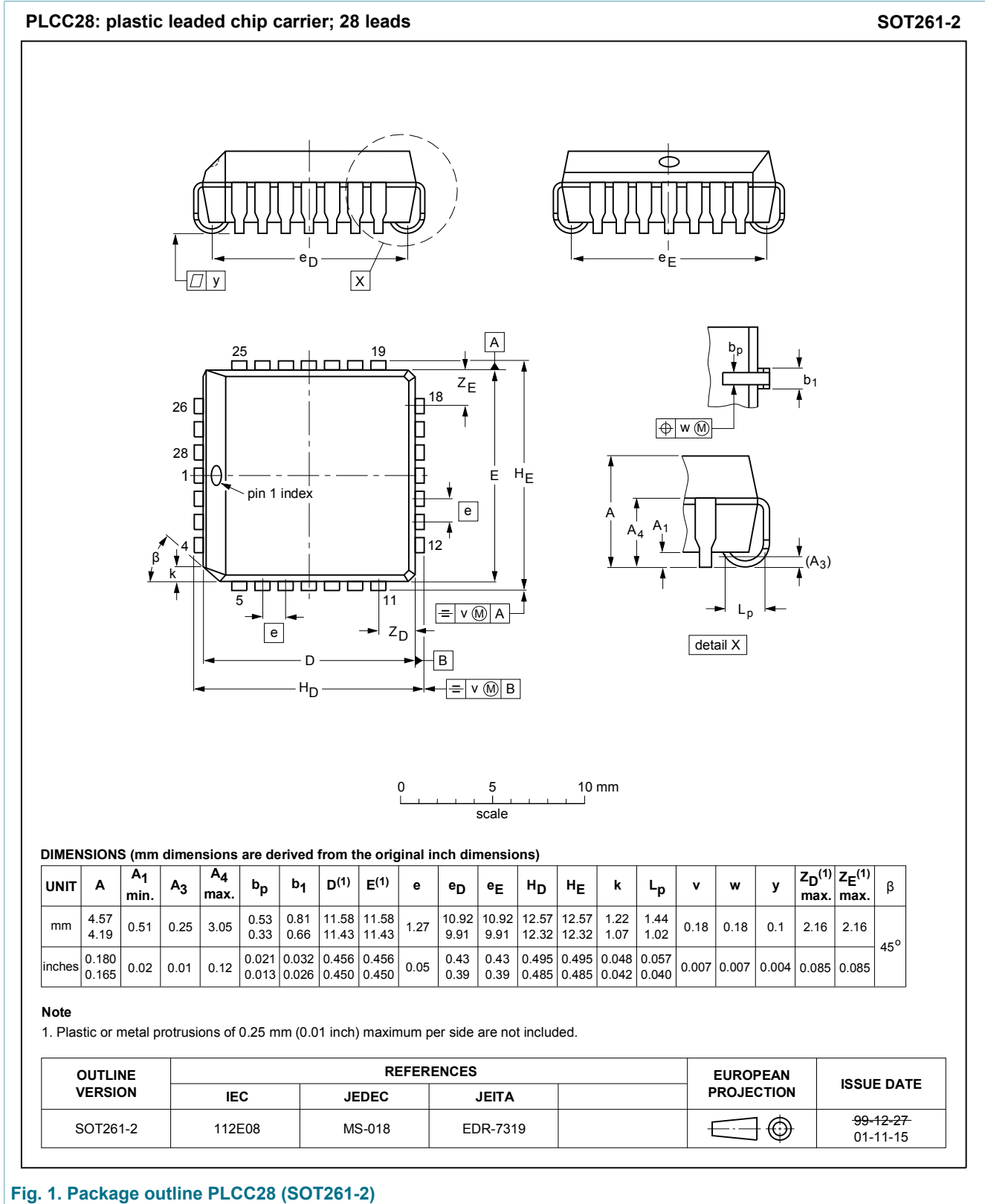


Fig. 1. Package outline PLCC28 (SOT261-2)

3. Soldering

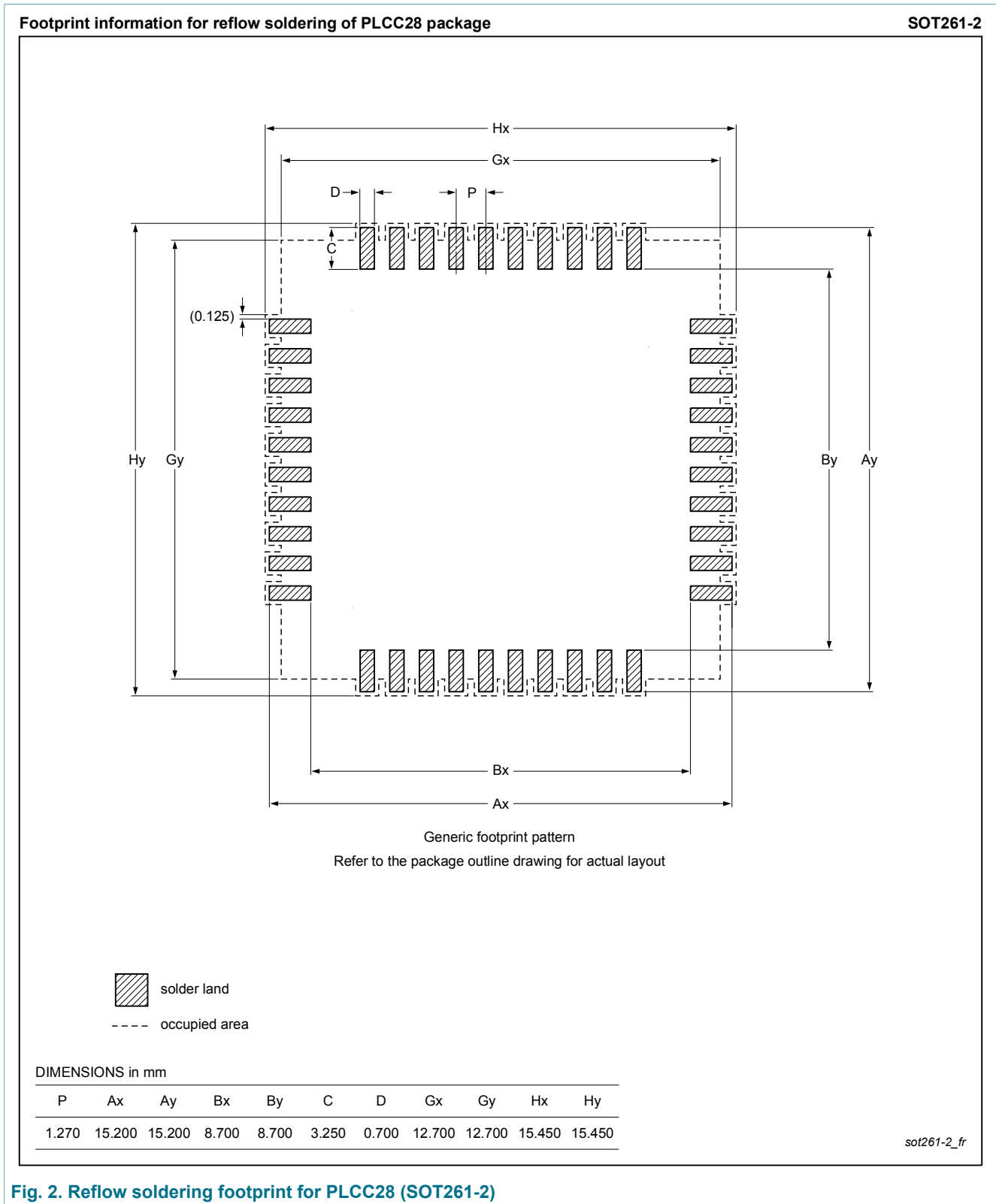


Fig. 2. Reflow soldering footprint for PLCC28 (SOT261-2)

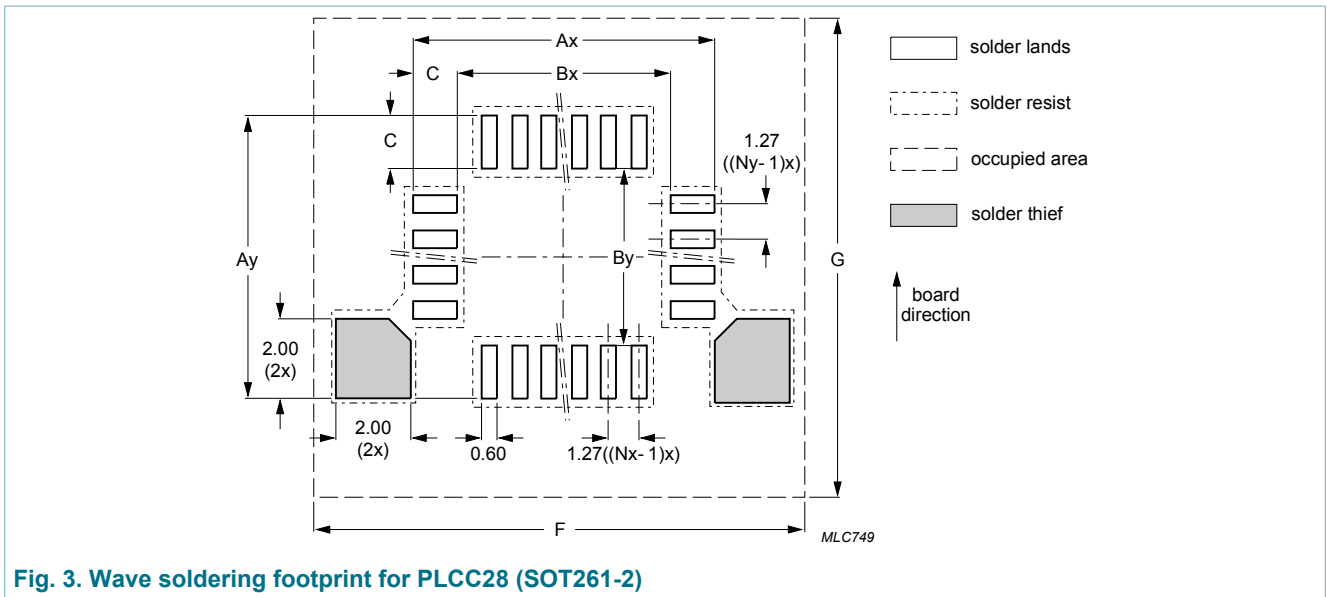


Fig. 3. Wave soldering footprint for PLCC28 (SOT261-2)

4. Legal information

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